# 2SB1180, 2SB1180A

# Silicon PNP epitaxial planar type darlington

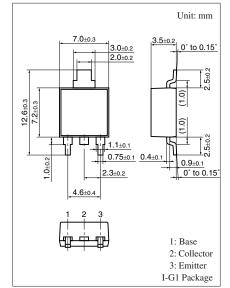
For medium-speed voltage switching Complementary to 2SD1750, 2SD1750A

# Features

- $\bullet$  High forward current transfer ratio  $h_{FE}$
- I type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment

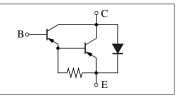
Parameter	Symbol	Rating	Unit				
Collector-base voltage	2SB1180	V <sub>CBO</sub>	-60	V			
(Emitter open)	2SB1180A		-80				
Collector-emitter voltage	2SB1180	V <sub>CEO</sub>	-60	V			
(Base open)	2SB1180A		-80				
Emitter-base voltage (Col	V <sub>EBO</sub>	-7	V				
Collector current	I <sub>C</sub>	-8	А				
Peak collector current	I <sub>CP</sub>	-12	А				
Collector power dissipation	P <sub>C</sub>	15	W				
	$T_a = 25^{\circ}C$		1.3				
Junction temperature	Tj	150	°C				
Storage temperature	T <sub>stg</sub>	-55 to +150	°C				

## Absolute Maximum Ratings $T_C = 25^{\circ}C$



Note) Self-supported type package is also prepared.

#### Internal Connection



## Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

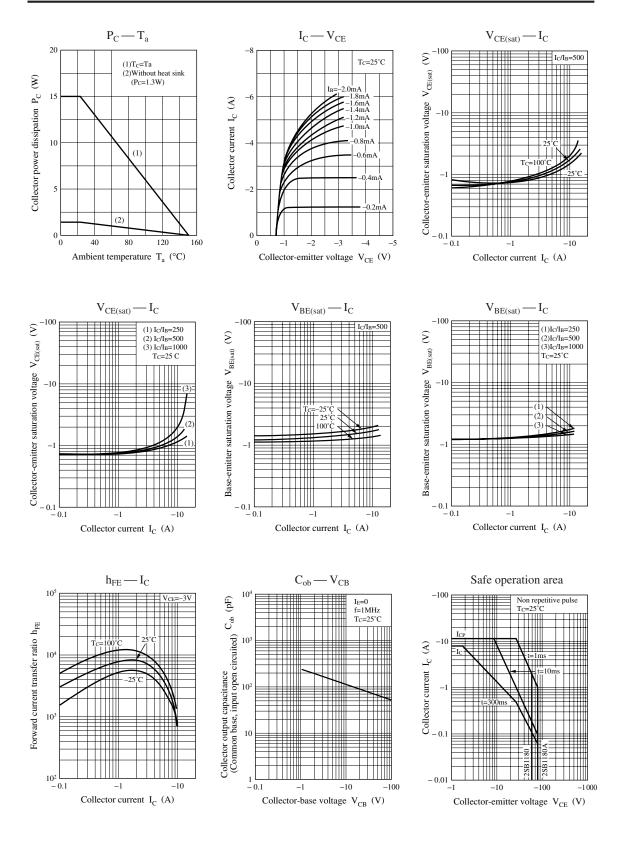
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage	2SB1180	V <sub>CEO</sub>	$I_{\rm C} = -30 \text{ mA}, I_{\rm B} = 0$	-60			V
(Base open)	2SB1180A			-80			
Collector-base cutoff	2SB1180	I <sub>CBO</sub>	$V_{CB} = -60 \text{ V}, I_E = 0$			-100	μΑ
current (Emitter open)	2SB1180A		$V_{CB} = -80 \text{ V}, I_E = 0$			-100	
Emitter-base cutoff current (Collector open)		I <sub>EBO</sub>	$V_{EB} = -7 V, I_C = 0$			-2	mA
Forward current transfer rat	io	h <sub>FE1</sub> *	$V_{CE} = -3 V, I_C = -4 A$	2000		10000	
		h <sub>FE2</sub>	$V_{CE} = -3 V, I_C = -8 A$	500			
Collector-emitter saturation	voltage	V <sub>CE(sat)</sub>	$I_{C} = -4 A, I_{B} = -8 mA$			-1.5	V
Base-emitter saturation volt	tage	V <sub>BE(sat)</sub>	$I_{\rm C} = -4$ A, $I_{\rm B} = -8$ mA			-2	V
Transition frequency		f <sub>T</sub>	$V_{CE} = -3 V, I_C = -1 A, f = 1 MHz$		20		MHz
Turn-on time		t <sub>on</sub>	$I_{C} = -4 \text{ A}, I_{B1} = -8 \text{ mA}, I_{B2} = 8 \text{ mA}$		0.5		μs
Storage time		t <sub>stg</sub>	$V_{CC} = -50 \text{ V}$		2.0		μs
Fall time		t <sub>f</sub>			1.0		μs

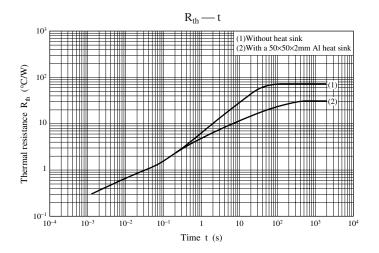
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*: Rank classification

Rank	Q	Р		
h <sub>FE1</sub>	2000 to 5000	4000 to 10000		

# Panasonic





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